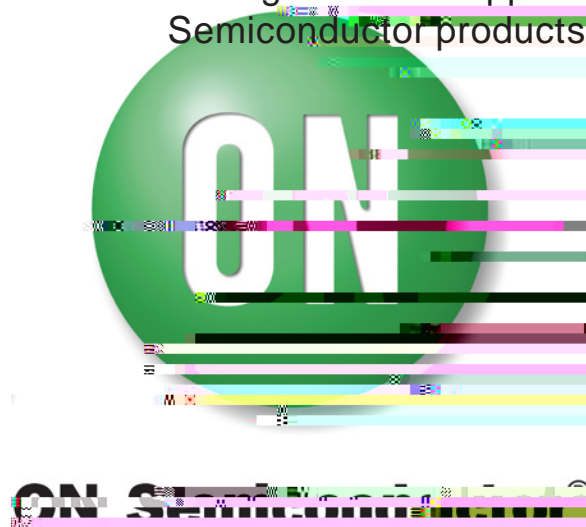


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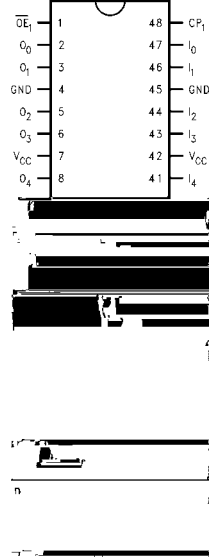
Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (_), the underscore (_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.onsemi.com. Please email any questions regarding the system integration to Fairchild_questions@onsemi.com.



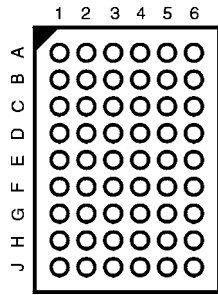
October 1997
Revised June 2005

Connection Diagrams

Pin Assignment for TSSOP



Pin Assignment for FBGA



(Top Thru View)

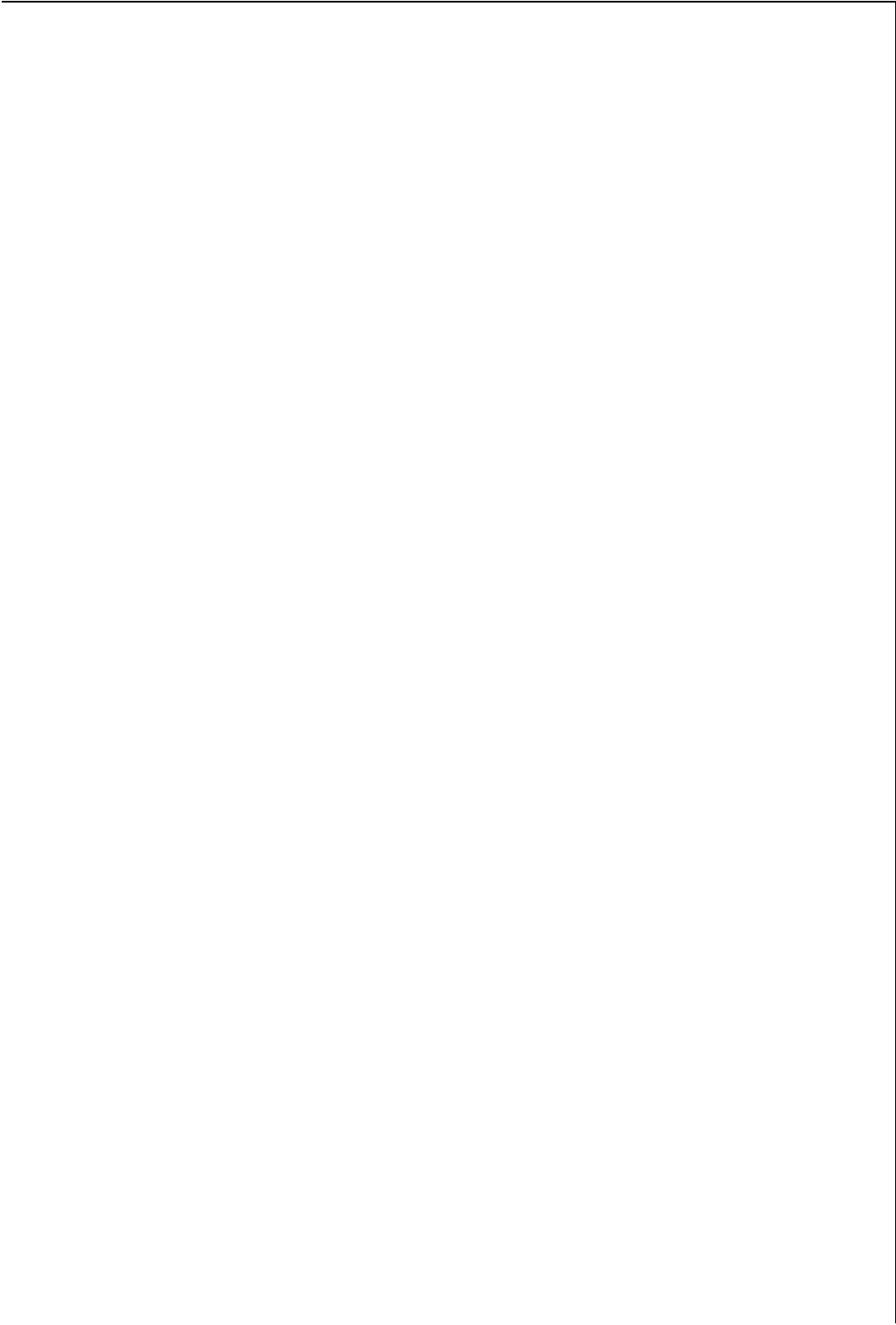
Pin Descriptions

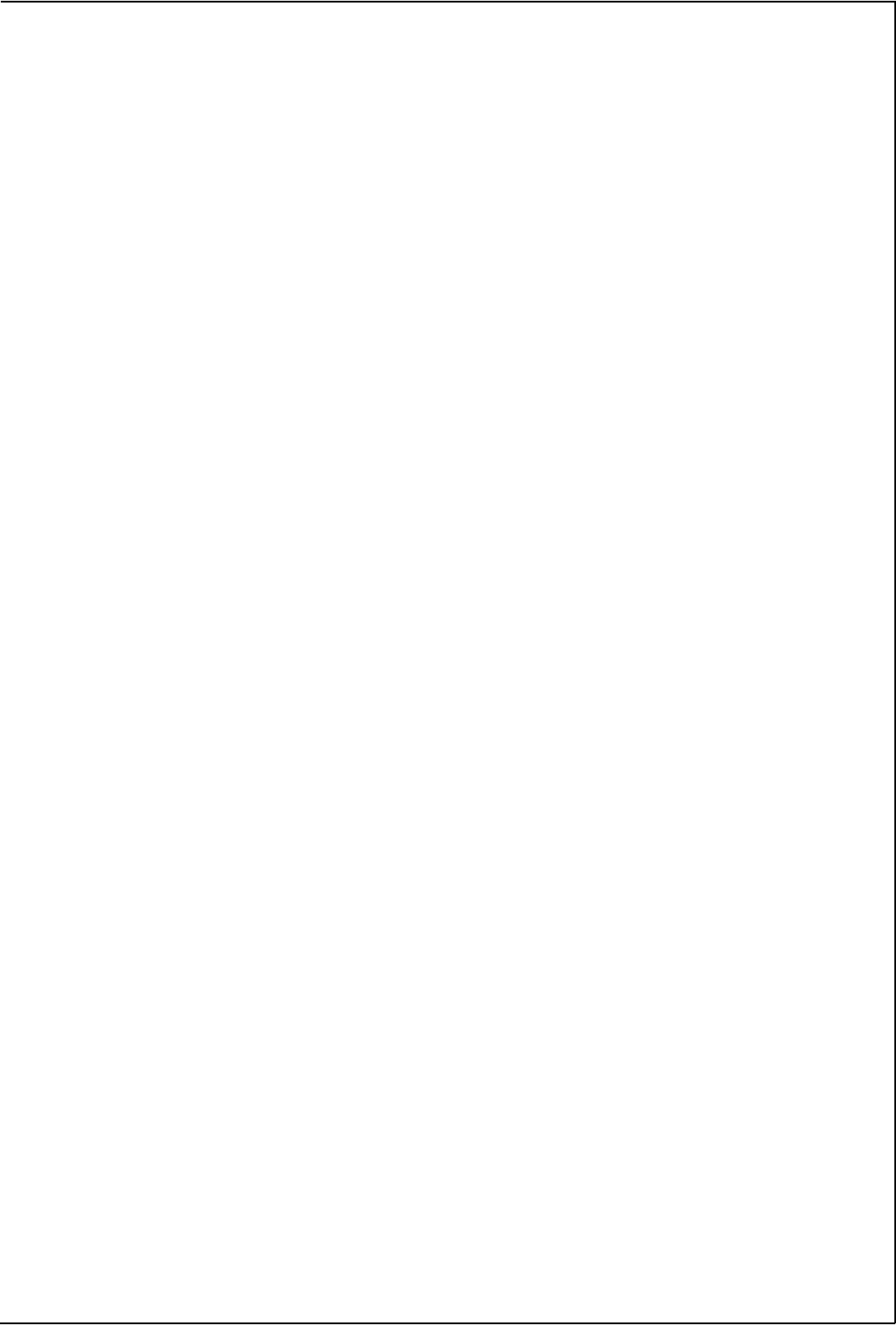
Pin Names	Description
\overline{OE}_n	Output Enable Input (Active LOW)
CP_n	Clock Pulse Tf 1.03013 Tc -0.00002 Tc -0.0111 p3013 T03013 Tt2.467 -1.28

FBGA Pin Assignments

Truth Tables

- H = HIGH Voltage Level
- L = LOW Voltage Level
- X = Immaterial (HIGH or LOW, inputs may not float)
- Z = High Impedance
- O₀ = Previous O₀ before HIGH-to-LOW of CP





DC Electrical Characteristics (Continued)

Symbol	Parameter	Conditions	V _{CC}	Min	Max	Units
			(V)			
V _{OL}	LOW Level Output Voltage	I _{OL} = 100 μA	2.7 - 3.6		0.2	V
		I _{OL} = 12 mA	2.7	0.4		
		I _{OL} = 18 mA	3.0	0.4		
		I _{OL} = 24 mA	3.0	0.55		
		I _{OL} = 100 μA	2.3 - 2.7	0.2		
		I _{OL} = 12 mA	2.3	0.4		
		I _{OL} = 18 mA	2.3	0.6		
		I _{OL} = 100 μA	1.65 - 2.3	0.2		
		I _{OL} = 6 mA	1.65	0.3		
		I _{OL} = 100 μA	1.4 - 1.6	0.2		
		I _{OL} = 2 mA	1.4	0.35		
		I _{OL} = 100 μA	1.2	0.05		
I _I	Input Leakage Current	0 ≤ V _I ≤ 3.6V	1.2 - 3.6		±5.0	μA
I _{OZ}	3-STATE Output Leakage	0 ≤ V _O ≤ 3.6V V _I = V _{IH} or V _{IL}	1.2 - 3.6		±10	μA
I _{OFF}	Power-OFF Leakage Current	0 ≤ (V _I , V _O) ≤ 3.6V	0		10	μA
I _{CC}	Quiescent Supply Current	V _I = V _{CC} or GND	1.2 - 3.6		20	μA
		V _{CC} ≤ (V _I , V _O) ≤ 3.6V (Note 7)	1.2 - 3.6		±20	
ΔI _{CC}	Increase in I _{CC} per Input	V _{IH} = V _{CC} - 0.6V	2.7 - 3.6		750	μA

Note 7: Outputs disabled or 3-STATE only.

AC Electrical Characteristics (Note 8)

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = -40°C to +85°C		Units	Figure Number
				Min	Max		
f _{MAX}	Maximum Clock Frequency	C _L = 30 pF, R _L = 500Ω	3.3 ± 0.3	250		ns	Figures 1, 2
			2.5 ± 0.2	200			
			1.8 ± 0.15	100			
t _{PHL} t _{PLH}	Propagation Delay CP to O _n	C _L = 15 pF, R _L = 2kΩ	1.5 ± 0.1	80		ns	Figures 7, 8
			1.2	40			
			3.3 ± 0.3	0.8	3.0		
t _{PZH} t _{PZL}	Output Enable Time	C _L = 30 pF, R _L = 500Ω	2.5 ± 0.2	1.0	3.9	ns	Figures 1, 2
			1.8 ± 0.15	1.5	7.8		
			1.5 ± 0.1	1.0	15.6		
t _{PHZ} t _{PLZ}	Output Disable Time	C _L = 15 pF, R _L = 2kΩ	1.5 ± 0.1	1.0	18.4	ns	Figures 7, 9, 10
			1.2	1.5	46		
			3.3 ± 0.3	0.8	3.5		
t _S	Setup Time	C _L = 30 pF, R _L = 500Ω	2.5 ± 0.2	1.0	3.8	ns	Figures 1, 3, 4
			1.8 ± 0.15	1.5	6.8		
			1.5 ± 0.1	1.0	13.6		
t _S	Setup Time	C _L = 15 pF, R _L = 2kΩ	3.3 ± 0.3	1.0	34	ns	Figures 7, 9, 10
			1.2	1.5	34		
			3.3 ± 0.3	1.8			

L

AC Electrical Characteristics (Continued)

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = -40°C to +85°C		Units	Figure Number
				Min	Max		
t _H	Hold Time	C _L = 30 pF, R _L = 500Ω	3.3 ± 1.0	1.0		ns	Figures 1, 6
			2.5 ± 0.2	1.0			
			1.8 ± 0.15	1.0			
t _W	Pulse Width	C _L = 15 pF, R _L = 2kΩ	1.5 ± 0.1	2.0		ns	Figures 6, 7
			1.2	6			
			1.8 ± 0.15	4.0			
t _W	Pulse Width	C _L = 30 pF, R _L = 500Ω	3.3 ± 0.3	1.5		ns	Figures 1, 4
			2.5 ± 0.2	1.5			
			1.8 ± 0.15	4.0			

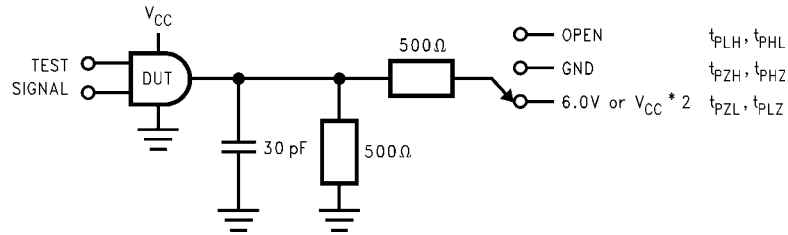
Note 8: For C_L = 50pF, add approximately 300 ps to the AC maximum specification.

Note 9: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}).

Dynamic Switching Characteristics

Capacitance

AC Loading and Waveforms (V_{CC} 3.3V ± 0.3V to 1.8V ± 0.15V)



TEST	SWITCH
t_{PLH}, t_{PHL}	Open
t_{PZL}, t_{PLZ}	6V at $V_{CC} = 3.3V \pm 0.3V$; $V_{CC} \times 2V$ at $V_{CC} = 2.5V \pm 0.2V; 1.8V \pm 0.15V$
t_{PZH}, t_{PHZ}	GND

FIGURE 1. AC Test Circuit

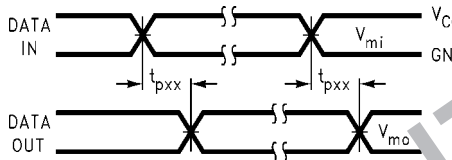


FIGURE 2. Waveform for Inverting and Non-Inverting Functions

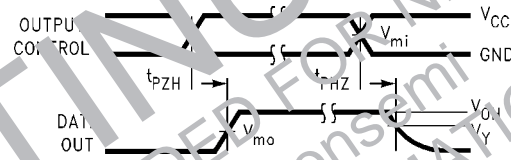


FIGURE 3. 3-STATE Output High Enable and Disable Times for Low Voltage Logic

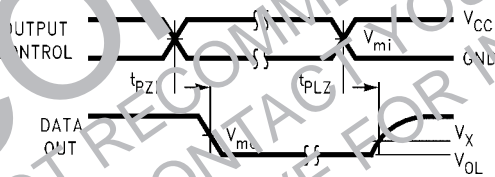


FIGURE 4. 3-STATE Output Low Enable and Disable Times for Low Voltage Logic

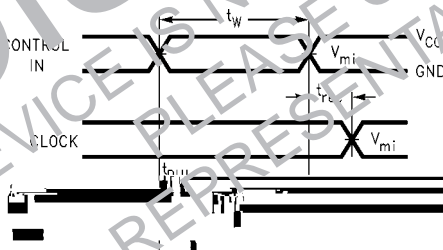


FIGURE 5. Propagation Delay, Pulse Width and t_{rec} Waveforms

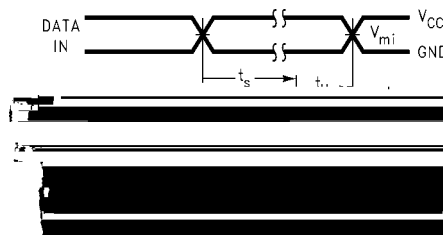


FIGURE 6. Setup Time, Hold Time and Recovery Time for Low Voltage Logic

Symbol	V_{CC}		
	3.3V ± 0.3V	2.5V ± 0.2V	1.8V ± 0.15V
V_{mi}	1.5V	$V_{CC}/2$	$V_{CC}/2$
V_{mo}	1.5V	$V_{CC}/2$	$V_{CC}/2$
V_X	$V_{OL} + 0.3V$	$V_{OL} + 0.15V$	$V_{OL} + 0.15V$
V_Y	$V_{OH} - 0.3V$	$V_{OH} - 0.15V$	$V_{OH} - 0.15V$

AC Loading and Waveforms ($V_{CC} 0.15V \pm 0.1V$ to $1.2V$)

TEST SWITCH
t

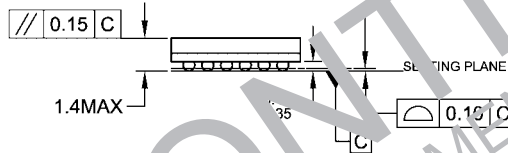
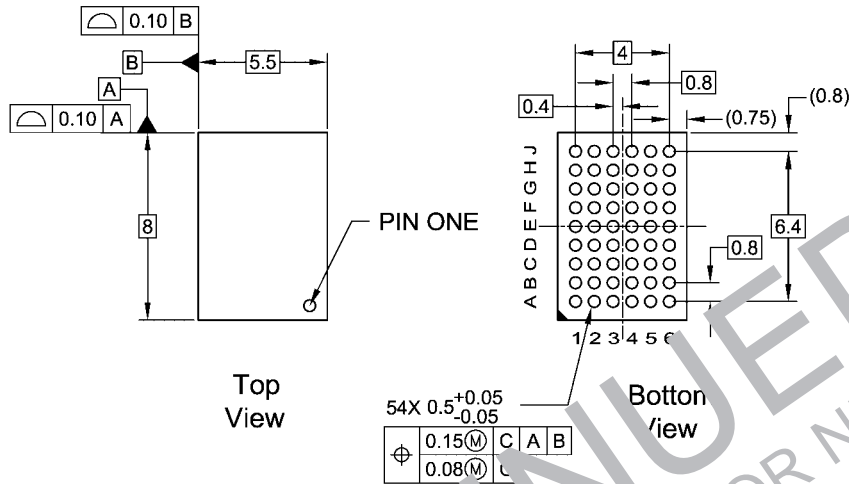
FIGURE 7. AC Test Circuit

FIGURE 8. Waveform for Inverting and Non-Inverting Functions

FIGURE 9. 3-STATE Output High Enable and Disable Times for Low Voltage Logic

FIGURE 10. 3-STATE Output Low Enable and Disable Times for Low Voltage Logic

Physical Dimensions inches (millimeters) unless otherwise noted



NOTE:
 THIS PACKAGE CONFORMS TO JEDEC MO-205

54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide
 Package Number BGA54A

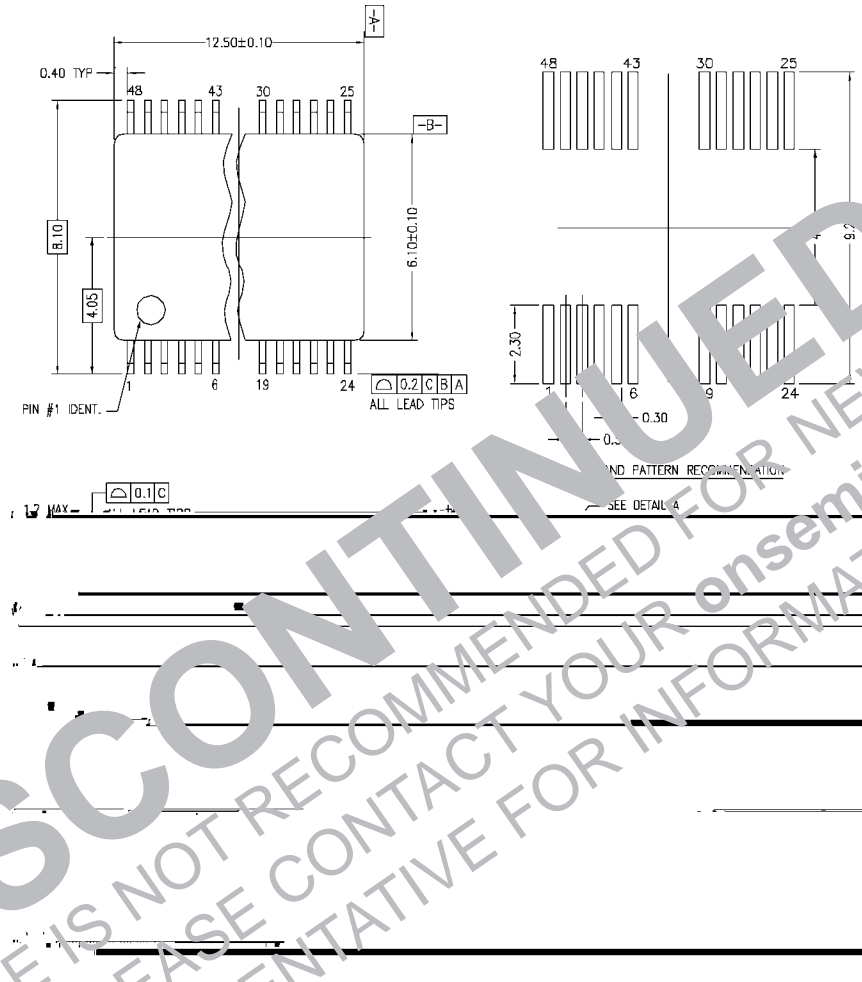
DISCONTINUED

THIS DEVICE IS NOT RECOMMENDED FOR NEW DESIGN

PLEASE CONTACT YOUR onsemi REPRESENTATIVE FOR INFORMATION

74VCM1634 Low Voltage 16-Bit D-Type Flip-Flops with 3.6V Tolerant Inputs and Outputs

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



4-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Body Width
Package Number MTD48

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